

	MODEL NAME		MATERIAL θ	ANGLE OF FLAT OR SLOT	SHAFT	15. SWITCH CIRCUIT	14. SWITCH WORKING TORQUE (FORCE)	13. SWITCH WORKING ANGLE (STROKE)	12. CLICK POSITION & TORQUE		II TERMINAL STRENGTH	10. SHAFT LEVER STOP STRENGTH	9. SHAFT LEVER WOBBLE	8. SHAFT LEVER STRENGTH	7. SLIDING FORCE	6. ROTATION TORQUE	5. SCREW TIGHTENING FORCE	4. NUT WIRING STRENGTH	3. TOTAL TRAVEL STROKE	2. TOTAL ROTATION ANGLE	I. OUTSIDE DIMENSION	1. MECHANICAL SPECIFICATION	CUSTOMER'S DRAWING NO.	CUSTOMER'S PART NAME	CUSTOMER'S NAME
	AME		at X	OR SLOT			FORCE) g.cm	TROKE) degree (mm)	JE g.cm	resist change within ± 2%	soldering heat 350±	more than 6		pulling pushing	speed 20mm/sec	speed 60 deg/sec	CE torsional moment	twisting moment	mm	degree	append fig	FICATION			
	DRAWING NO.	21	L F T	DIMENSION						in ± 2%	more man 300 g.cm / 10 ± 1 sec soldering heat 350±5°C/3sec, 2009 cm/10±1sec	kg.cm (static load) / 60		ing more than	sec	sec. 20-200	ent less than	ent less than 9		300	i de				NOIF
Je III	Ш					<u>_</u>	ų.	[5,	12	F	10.	sec	g.cm) 8.	kg 7.	g.cm 6,	g.cm &	kg.cm 5.	kg.cm 4.	±0.5 3.	t5 2	-	2.			
1	REFERENCE NO.		SW LIFE ± TIMES CONTACT RESISTANCE: less than		RESISTANCE CHANGE: within ±	4. VR LIFE 15,000 ±	3. USABLE TEMPERATURE RANGE: from -10°C to 70°C	13. SWITCH RAITING	12. SWITCH CONTACT RESISTANCE	II. TRACKING ERROR	10. WITHSTAND VOLTAGE	9. INSULATION RESISTANCE	8. SLIDE NOISE	7. TAP RESIDUAL RESISTANCE	6. RESIDUAL RESISTANCE	& TOLERANCE	5. RESISTANCE TAPER MEASURING POINT	4. MAXIMUM WORKING VOLTAGE	3. RATED WATTAGE	2. TAP RESISTANCE & TOLERANCE	I. OVERALL RESISTANCE & TOLERANCE	2. ELECTRICAL SPECIFICATION			
			TIMES ISTANCE: less th	SLIDE NOISE : less than	HANGE: within	TIMES	GE: from -10°C to		MΩ		AC 500	more than 100	speed 60° / 1 sec	terminal 4 side	terminal 1/3 side				temp 0-50°C	terminal 1-4	terminal 1-3				
	REV		B		17		70°C		less than		V 1	MΩ(DC	less than	less than	less than	10	50	250	0.25	ດ	ω MI				DALE
			<b>B</b>	mV	%				mΩ		minute	500	47 mV	-	30/50	~ 25 %	%point	٧	W	Ω±	Ω± 30				

## 可變電阻無鉛焊錫共通規格書

## Common Specification of Lead-Free Soldering for Potentiometers

以下焊錫條件以可變電阻置於單層 1.6mm 厚度之印刷電路板上測試爲基準.

The specification below is based on testing results of 1.6mm thickness single layer printed circuit board.

1. 手工焊錫條件:

For Manual Soldering:

1-1 操作溫度最高 350°C,操作時間 3 秒以內。

To be performed within 3 seconds at 350°C or below.

2. 自動或半自動機台焊錫條件:

For Automated or Semi-Automated Soldering Equipments:

2-1 使用發泡式且比重 0.82 以上的助焊劑,發泡高度以印刷電路板厚度一半為標準,且助劑不能流入可變電阻基板表面及印刷電路板表面。

Flux of 0.82 specific gravity, applied by foam fluxer, shall be used. Foam head shall be limited to the height which is half thickness of printed circuit board to be soldered. No flux should be allowed to run up onto resistive element board of potentiometer and the surface of printed circuit board.

- 2-2 預熱時間不超過兩分鐘, 焊錫接面 (即印刷電路板底) 最高預熱溫度不超過 100°C。
  Regarding preheating, the entire flow duration should not exceed 2 minutes, and soldering surface temperature (undersurface of PCB) shall be settled within 100°C.
- 2-3 焊錫過程機台設定溫度在 260°C 以下、 4 秒以內。
  Solder Dipping is to be performed within 4 seconds at 260°C or below.
- 3. 若回轉型電位器是塑膠軸且帶有檔位,請將主軸先調整至其中一個檔位或中心檔位上才可以 進行焊錫作業。

For rotary potentiometer with plastic shaft which have centre detent or multiple detents, the shaft should be settled in relevant detent position prior to soldering process.

4. 手工焊錫、自動或半自動機台焊錫不得超過一回。

Regardless of soldering facility and method, solder dipping or solder smearing must not be carried out more than 1 time.

註: 本項焊錫溫度條件不適用於回流焊接作業設備。

Remarks: This specification is not recommended for and applicable in reflow

soldering.

焊錫注意事項:

Caution for soldering:

如圖所示,請避免 PCB 上層表面有焊錫 Please avoid soldering on upper surface of P.C.B. as shown.

